



SOT1380-1

wafer level chip-scale package; 6 bumps; 0.69 mm x 1.09 mm
x 0.38 mm

24 November 2016

Package information

1. Package summary

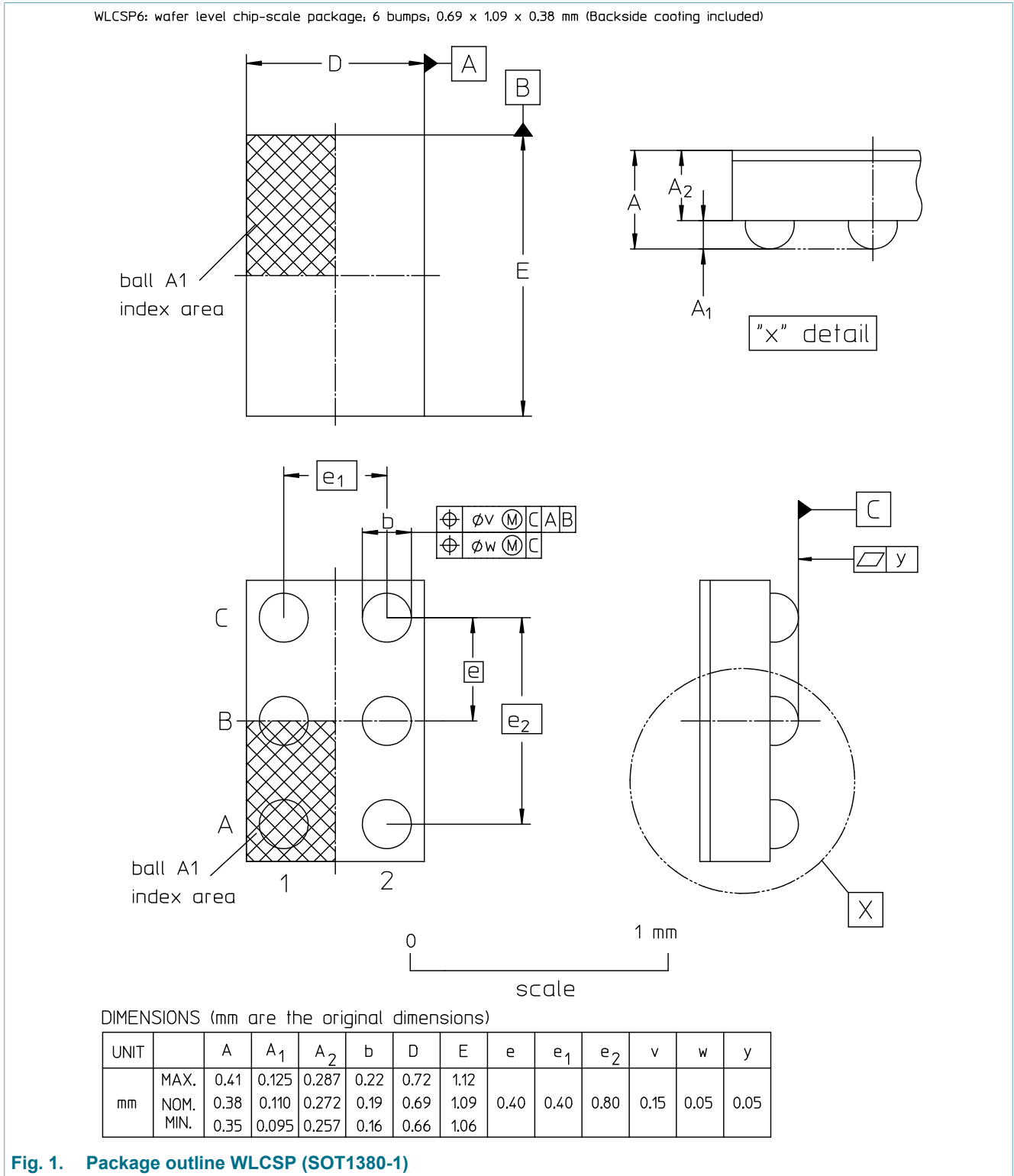
Terminal position code	B (bottom)
Package type descriptive code	WLCSP6
Package type industry code	WLCSP
Package style descriptive code	WLCSP
Package body material type	X (other)
Mounting method type	S (surface mount)
Issue date	24-11-2016
Manufacturer package code	SOT1380

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	0.66	-	0.69	0.72	mm
E	package width	1.06	-	1.09	1.12	mm
A	seated height	0.35	-	0.38	0.41	mm
A ₂	package height	0.257	-	0.272	0.287	mm
e	nominal pitch	-	-	0.4	-	mm



2. Package outline



3. Legal information

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